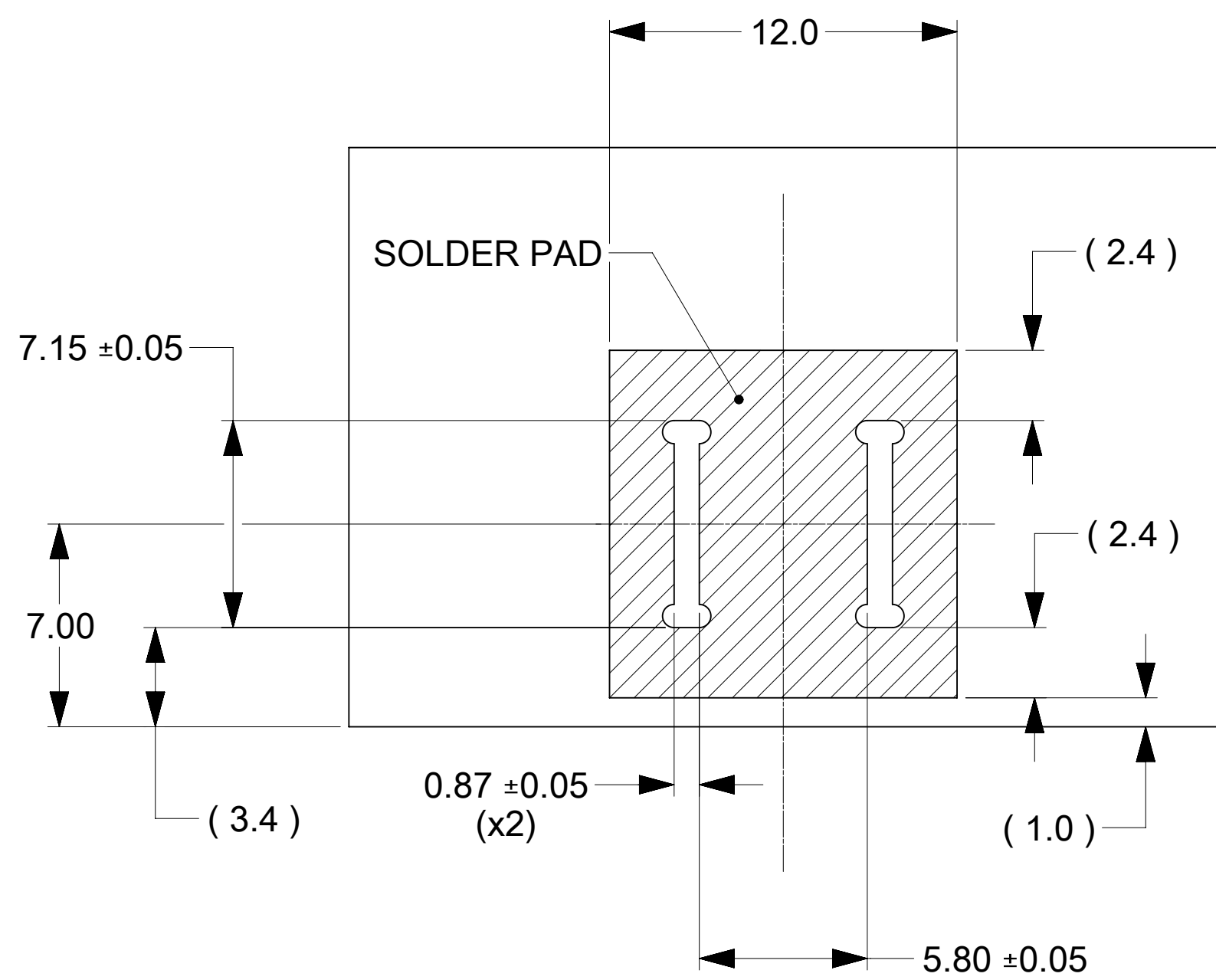
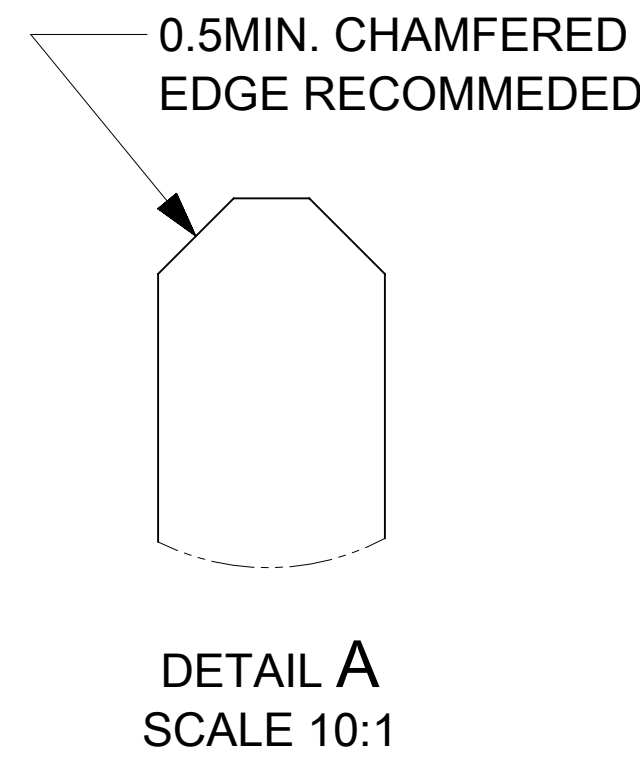


PART NUMBER	PLATINGS ON THE CONTACT AREAS
213205-0002	SILVER OVER NICKEL
213205-0102	TIN OVER NICKEL

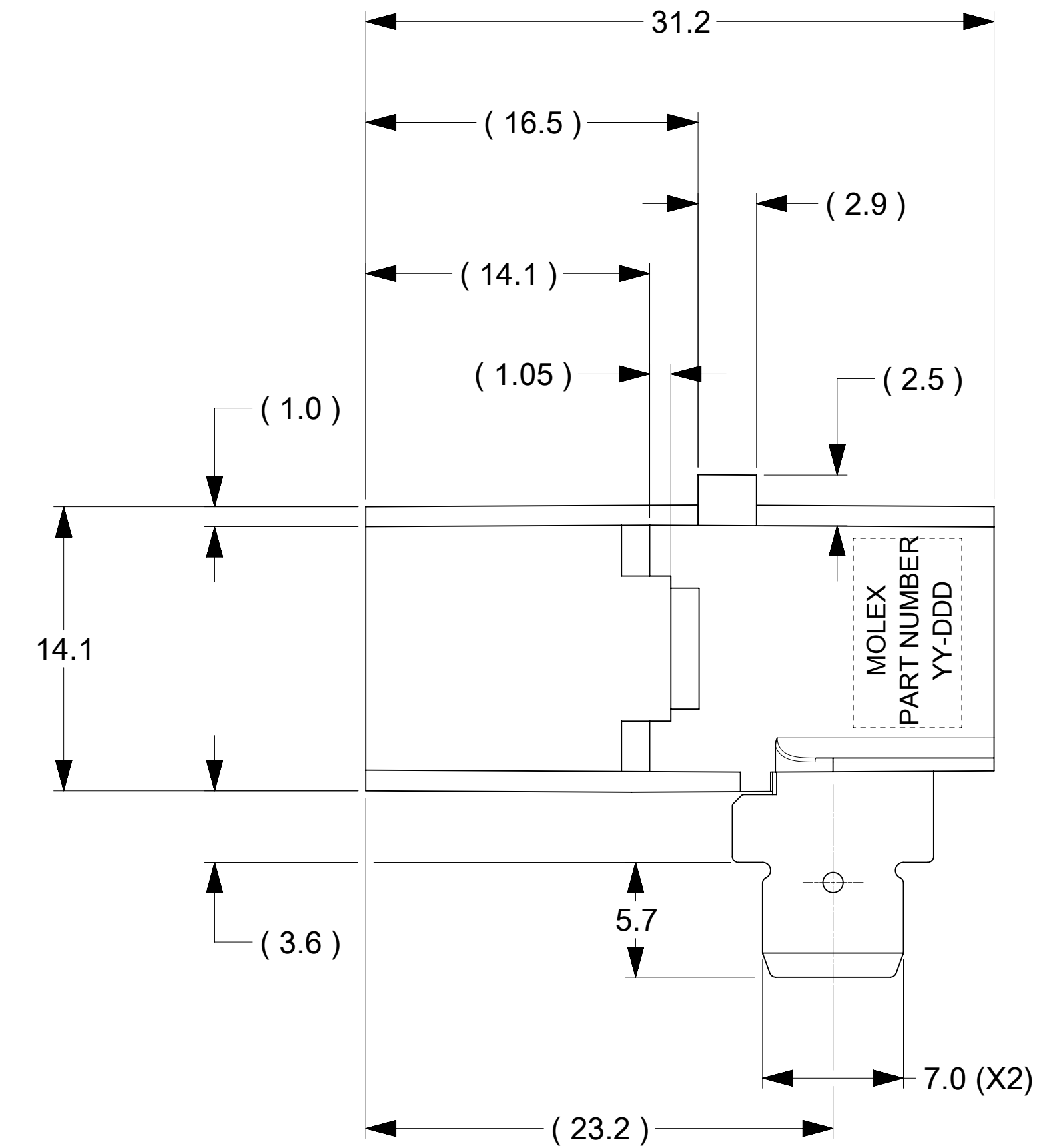
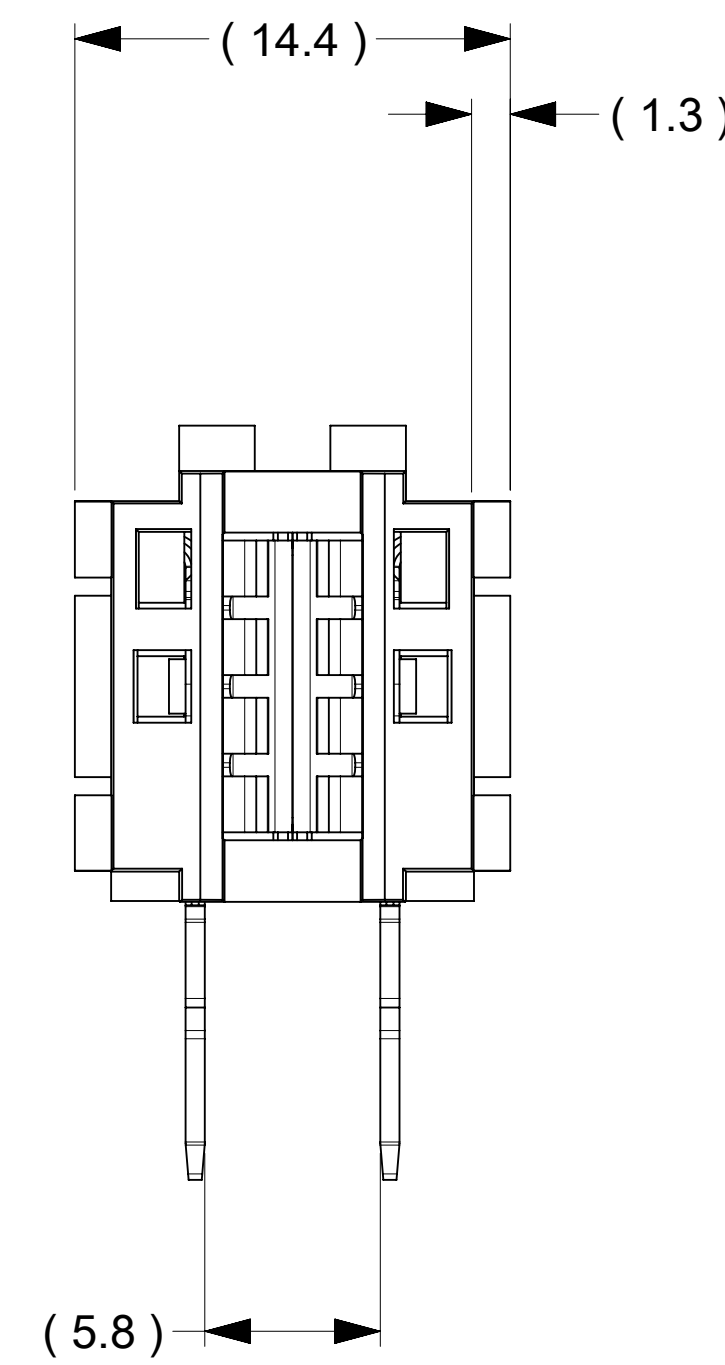
PCB, BUSBAR
IN THESE VIEWS ARE SHOWN FOR REFERENCE ONLY



RECOMMENDED PCB LAYOUT
(THICKNESS 4.8mm MAX.)



- NOTES:
- MATERIALS:
 - HOUSING BODY: POLYMER. UL94V-0; BLACK.
 - TERMINALS: COPPER ALLOY.
 - RIVET/CLIP: COPPER ALLOY.
 - PLATING:
 - CONTACT AREAS:
 - OPTION 1: 3.18 MICRON MIN. SILVER, OVER 1.27 MICRON MIN. NICKEL.
 - OPTION 2: 2.50 MICRON MIN. MATTE TIN OV34 1.27 MICRON MIN. NICKEL.
 - TAB AREAS: 3.18 MICRON MIN. TIN OVER 1.27 MICRON MIN. NICKEL.
 - REST: 1.27 MICRON MIN. NICKEL.
 - LUBRICATION: LUBED IN CONTACT AREA.
 - REFERENCE DOCUMENT:
 - SILVER VERSION: 2131910001-PS, 2131910001-AS.
 - TIN VERSION: 2131910002-PS, 2131910001-AS.
 - MODULE ASSEMBLY IS RoHS COMPLIANT.
 - FINAL ASSEMBLY TO BE PACKAGED AND LABELED PER PACKAGING DRAWING NUMBER 2131910002-PK.
 - MATED BUSBAR SHOULD BE PLATED WITH SILVER OVER NICKEL FOR SILVER VERSION CONNECTOR AND TIN OVER NICKEL FOR TIN VERSION CONNECTOR.



FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC:	
$F_A = 0$	mm	SCALE	5:1	
$F_C = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)			
$F_D = 0$	ANGULAR TOL	±	°	
DIVISIONAL SYMBOLS	4 PLACES	±		
	3 PLACES	±		
	2 PLACES	±	0.15	
	1 PLACE	±	0.25	
	0 PLACES	±		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER
		D-SIZE	213205	SEE CHART
				CUSTOMER
				SHEET NUMBER
				1 OF 1

molex

POWER PLANE BBC SMALL RA-TH

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER	DOC TYPE	DOC PART	REVISION
2132050002-SD	PSD	000	C